

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	12	(("6,162,652") or ("5,756,370") or ("5,554,940") or ("5,665,639") or ("5,633,535") or ("6,103,552")).PN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 12:36
L2	2252415	@ad>"20030319" @rlad>"20030319" @pt1d>"20030319"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 12:36
L3	2	pedestal with (ubm blm) with (nickel nickel ni) not L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 12:37
L4	18	("5554940" "5656858" "5747881" "5756370" "6157079" "6162652").PN. OR ("6426556").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/09 12:38
L5	18	("5554940" "5656858" 4 not 2"5747881" "5756370" "6157079" "6162652").PN. OR ("6426556").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/09 12:38
L6	15	(US-20020086520-\$ or US-20020096764-\$ or US-20030025202-\$ or US-20030094963-\$ or US-20030129821-\$ or US-20030166330-\$ or US-20030222352-\$ or US-20020121692-\$).did. or (US-6399475-\$ or US-6452270-\$ or US-6664128-\$ or US-6720243-\$ or US-6878963-\$ or US-6076723-\$ or US-5234153-\$).did.	US-PGPUB; USPAT	OR	ON	2005/11/09 13:02
S1	2244284	@ad>"20030319" @rlad>"20030319" @pt1d>"20030319"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 10:32
S2	2	(*20040183195).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/04 11:41
S4	0	((titanium ti titanium adj tungsten ti adj w chromium cr titanium adj nitride tantalum adj nitride tantalum ta aluminum al copper cu) adj (nickel ni) adj (vanadium v) adj (nickel ni) adj (gold au) not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:51
S5	0	((titanium ti titanium adj tungsten ti adj w chromium cr titanium adj nitride tantalum adj nitride tantalum ta aluminum al copper cu) with adhesion) and ((nickel ni) adj (vanadium v) with barrier) and ((nickel ni) with wetting) and ((gold au) with \$5oxidiz\$5) not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:54
S6	0	((titanium ti titanium adj tungsten ti adj w chromium cr titanium adj nitride tantalum adj nitride tantalum ta aluminum al copper cu) with adhesion) and ((nickel ni) adj (vanadium v) with barrier) and ((nickel ni) with wetting) and ((gold au) with \$oxidiz\$5) not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:55
S7	11	((titanium ti titanium adj tungsten ti adj w chromium cr titanium adj nitride tantalum adj nitride tantalum ta aluminum al copper cu) with adhesion) and ((nickel ni) adj (vanadium v) with barrier) and ((nickel ni) with wetting) and (gold au) not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:57
S13	2196003	semiconductor integrated adj circuit ic *438*/\$.cccls. *257*/\$.cccls. 228/180.22.cccls. not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:08
S17	31234	(tin sn) with (silver ag) with (copper cu) snagcu not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:05
S18	1168	(tin sn) adj (silver ag) adj (copper cu) snagcu not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:04
S19	0	(S17 S18) and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:05
S20	717	S13 and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:05
S21	608	(bump ball) and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:05
S22	519	S21 and S13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:06

S24	288	(anti adj oxid\$5 antioxid\$5) with (gold au) not S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 15:10
S25	0	S24 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:08
S26	3	S24 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:08
S28	2854	interposer and ("438"/\$.ccls: "257"/\$.ccls:)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:49
S29	12	(US-20030166330-\$ or US-20030222352-\$ or US-20030129821-\$ or US-20030094963-\$ or US-20030025202-\$ or US-20020096764-\$ or US-20020086520-\$).did. or (US-6399475-\$ or US-6878963-\$ or US-6720243-\$ or US-6664128-\$ or US-6452270-\$).did.	US-PGPUB; USPAT	OR	ON	2005/11/04 15:10
S30	12	((anti adj oxid\$5 antioxid\$5) gold au) and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 15:11
S31	2	(anti adj oxid\$5 antioxid\$5) and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 16:15
S40	12	(US-20020086520-\$ or US-20020096764-\$ or US-20030025202-\$ or US-20030094963-\$ or US-20030129821-\$ or US-20030166330-\$ or US-20030222352-\$).did. or (US-6399475-\$ or US-6452270-\$ or US-6664128-\$ or US-6720243-\$ or US-6878963-\$).did.	US-PGPUB; USPAT	OR	ON	2005/11/08 20:06
S41	9	(thick\$5 thin\$5) and S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 20:19
S42	2252415	@ad>"20030319" @rad>"20030319" @pt1d>"20030319"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 20:21
S43	32	wetting near5 (ni nickel nickle) with (thin\$5 thick\$5) not S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 20:56
S44	1	wetting adj barrier adj post	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 20:57
S45	2	wetting with barrier with adhesion with (thin\$5 thick\$5) not S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 21:00
S46	892	wetting and barrier and adhesion with (thin\$5 thick\$5) not S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 12:31